H-putty2

Thermal Conductive Putty

LiPOLY H-putty2 is a one-part, dispensable thermally conductive putty. With a thermal conductivity from 6.0 W/m*K this product can be used successfully to remove manufacturing tolerances. It is ideally suited for dispensing using the H-putty2 dispensing robot.

Features-

- Thermal conductivity:6.0 W/m*K
- Bond Line Thickness:100-3000μm
- Designed to remove manufacturing tolerances
- Does not produce stress on delicate components
- No vertical flow
- Dispensable for serial manufacture

Typical Applications-

- For any high compression and low stress application
- Set-top box
- IP CAM

Configurations-

- Cartridges: 30ml, 55ml, 330ml
- Bucket: 1kg, 25kg

Preservation-

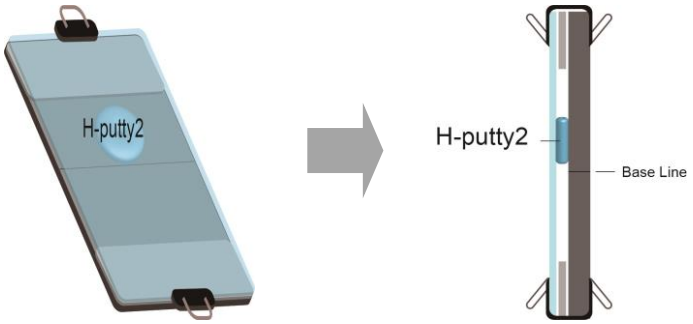
It can be preserved for 60 months under the condition of unopened and under room temperature 25℃.

Typical Properties-

PROPERTY	H-putty2	TEST METHOD	UNIT
Color	Blue	Visual	-
Resin Base	silicone	-	-
Viscosity	15000	DIN 53018	Pa.s
Density	3.3	ASTM D792	g/cm^3
Application temperature	-60~180	-	℃
Bond Line Thickness	100~3000	-	μm
Shelf Life	60 months	-	-
ROHS&REACH	yes	-	-
ELECTRICAL			
Dielectric breakdown	300	ASTM D149	V/mil
Volume resistivity	>10^{13}	ASTM D257	Ohm-m
THERMAL			
Thermal Conductivity	6.0	ASTM D5470	W/m*K
Thermal impedance@10psi	0.061	ASTM D5470	℃-in^2/ W
Thermal impedance@30psi	0.054	ASTM D5470	℃-in^2/ W
Thermal impedance@50psi	0.050	ASTM D5470	℃-in^2/ W

Vertical Reliability-

Using 3.0mm pad as a gap control, put the putty between the aluminum and the glass panel mark the initial position. Then, place it in the oven with 125 ℃ for 1,000 hours and observe its displacement after reliability test



Material no dropped or changed after high temperature aging testing